

TECHNICAL DATASHEET

Trade name:
Article No:
Issue:
File Name:

MARTIN solder paste **lead free**, rosin based
VD90.0230
February, 2015
TDS Lotpaste LF 02xx-e 2015_02_25.doc

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Description

Solder paste for printing purpose with low activated rosin based flux (halogen free)

Application Range

Solder paste for a wide range of high quality processes including electronic connections, electro - mechanical and mechanical solder applications.

Physical Characters

Metal Powder

- **Particle size** 20-38 µm
- **Alloy** Sn96,5 Ag3 Cu0,5
- **Melting Point** Solidus 217 - 218°C, Liquidus 219°C
- **Density** 5,0g/cm³ @ 20°C

Solder Paste

- **Metal Content** 85 - 89%
- **Viscosity** 120 Pas (Malcam spiral Type viscometer, PCU-2 @ 25°C, 10RPM)
- **Density** n/a
- **Package** 5ccm cartridge

Flux activity

- **Standard** ANSI- J-STD-004
- **Classification** ROL 0

Shelf Life / Time of Storage

- **Storage Temp:** 5 to 10 °C
- **Self life time** 3 month (sealed)
- **General:** Do not freeze.
Store syringes vertically, with tip down.
Avoid exposure to sunlight and high humidity.

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Cleaning

The flux residues don't need to be cleaned. They may remain on the circuit or removable with typical rosin cleaning solution.

Application

Dispense (Time Pressure Technology)

- **Nozzle Diameter** **not recommended**
- **Pressure** **not recommended**
- **Nozzle Heating** **not recommended**

Pinting

- **Recommended Product for printing application.**

General Handling Information

Ensure that the paste has reached room temperature before opening to get the paste dispensable and to prevent condensation.